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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Ray *et al.*

Examiner: Nguyen, Ha T

Serial No.: 09/779,812

Art Unit: 2812

Filed: 2/08/01

For: **LEAD-FREE SOLDER STRUCTURE AND METHOD FOR HIGH FATIGUE LIFE**

Commissioner for Patents
Washington D.C. 20231

Sir:

This paper is being filed in response to the Office Action mailed June 14, 2002. Applicants respectfully request that the above-identified application be reconsidered in view of the Amendments and Remarks that follow, that each of the presently pending claims be allowed, and that the application be passed to issue.

Amendment

Please amend the above-referenced patent application as follows:

In the Claims:

Please amend claims 25-29 as marked up in Appendix A. Please add new claims 35-36.

Pending claims 1-10 and 12-36 are as follows based on the amendment herein:

1. A method for forming an electronic structure, comprising the steps of:

providing a substrate; and

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